



SOT917-3

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN20
Package type industry code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	21-3-2011

Table 1. Package summary

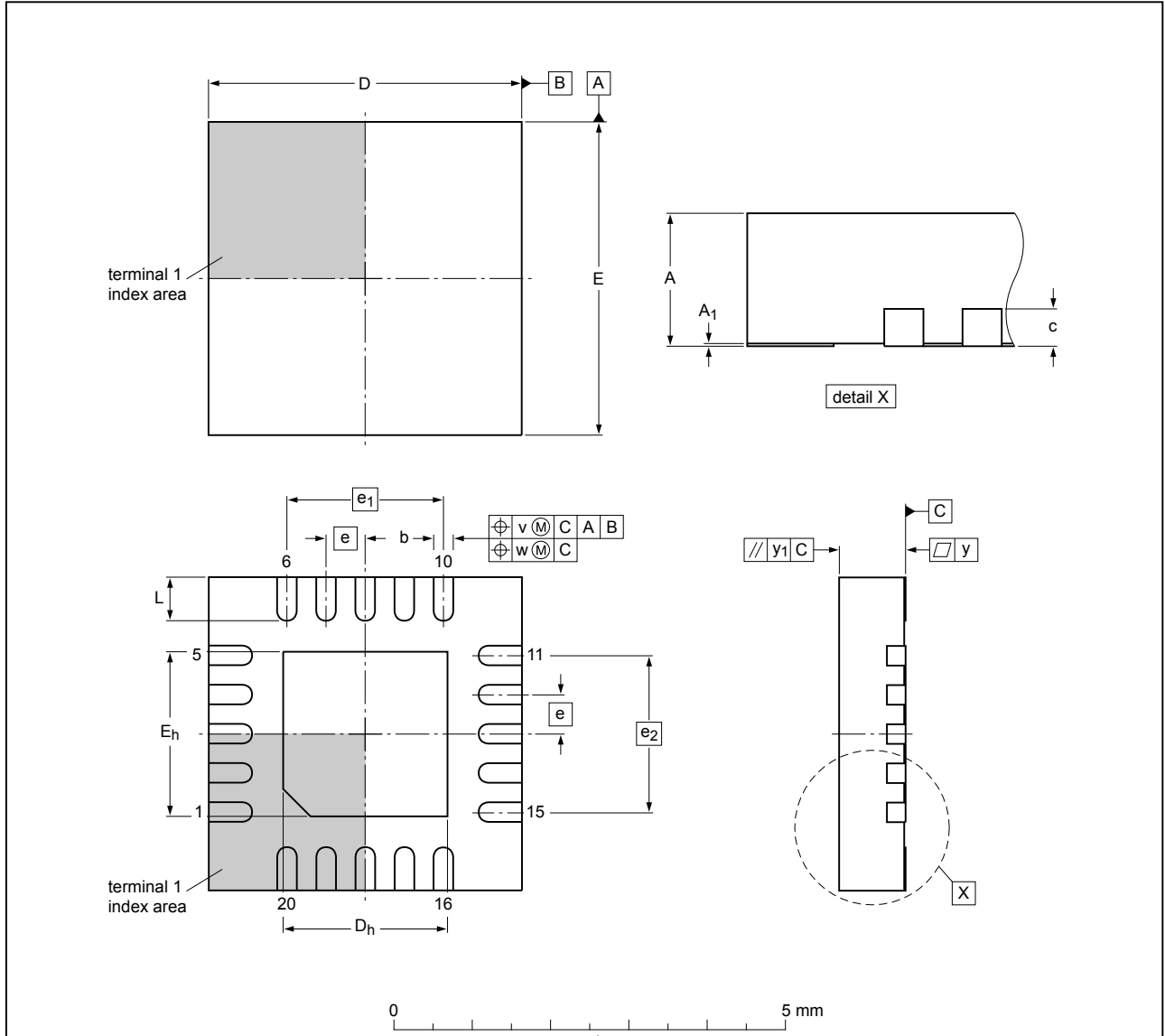
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

HVQFN20: plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 4 x 4 x 0.85 mm

SOT917-3



Dimensions

Unit	A	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		4.1	2.2	4.1	2.2				0.65				
mm nom	0.85	0.02	0.25	0.24	4.0	2.1	4.0	2.1	0.5	2	2	0.55	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20		3.9	2.0	3.9	2.0				0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot917-3_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT917-3		MO-220	---		11-03-14 11-03-21

Fig. 1. Package outline HVQFN20 (SOT917-3)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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